

## Evonik Corporation Compimide® 1206R55 Bismaleimide

Category : Polymer , Thermoset , Polyimide, TS

### Material Notes:

Compimide® 1206R55 is a heat-curable formulated bismaleimide resin supplied as a solution in N,N-dimethylformamide. It is recommended for the manufacture of printed wiring boards (PWB) via the prepreg route. Compimide® 1206R55 can also be formulated with epoxy resins to improve their temperature resistance.

Order this product through the following link:

[http://www.lookpolymers.com/polymer\\_Evonik-Corporation-Compimide-1206R55-Bismaleimide.php](http://www.lookpolymers.com/polymer_Evonik-Corporation-Compimide-1206R55-Bismaleimide.php)

Physical Properties	Metric	English	Comments
Viscosity	40 - 90 cP	40 - 90 cP	
	@Temperature 25.0 °C	@Temperature 77.0 °F	

Processing Properties	Metric	English	Comments
Gel Time	>= 15.0 min	>= 15.0 min	
	@Temperature 170 °C	@Temperature 338 °F	

Descriptive Properties	Value	Comments
Resin Content	55±2 wt%	

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